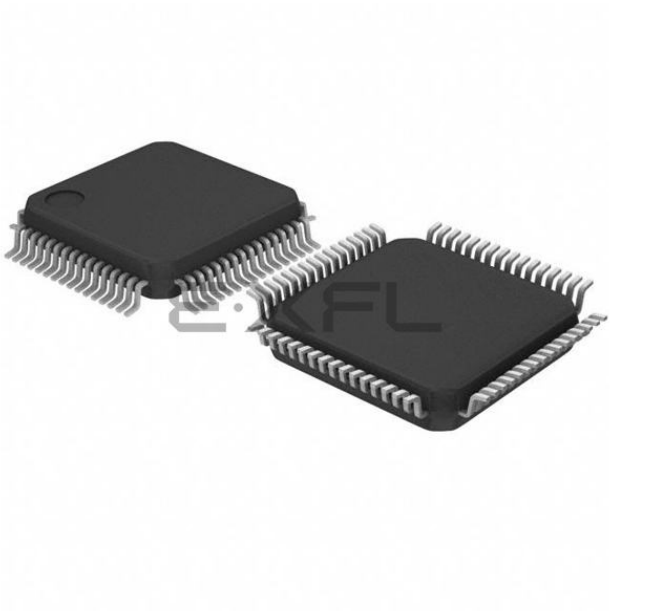


What is "Embedded - Microcontrollers"?

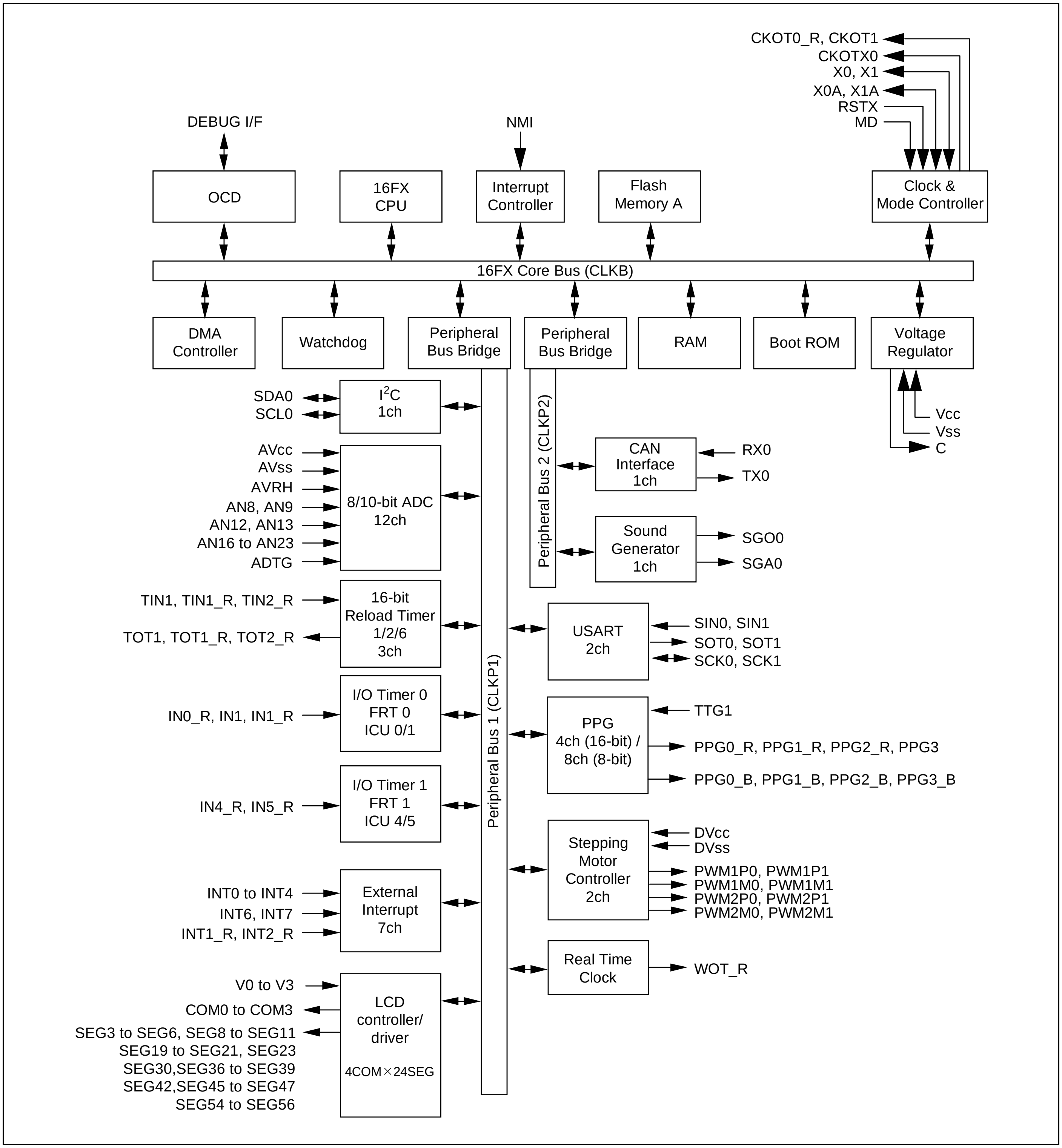
"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Obsolete
Core Processor	F²MC-16FX
Core Size	16-Bit
Speed	32MHz
Connectivity	CANbus, I²C, LINbus, SCI, UART/USART
Peripherals	DMA, LCD, LVD, POR, PWM, WDT
Number of I/O	50
Program Memory Size	96KB (96K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	4K x 8
Voltage - Supply (Vcc/Vdd)	2.7V ~ 5.5V
Data Converters	A/D 12x8/10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 105°C (TA)
Mounting Type	Surface Mount
Package / Case	64-LQFP
Supplier Device Package	64-LQFP (10x10)
Purchase URL	https://www.e-xfl.com/product-detail/infineon-technologies/mb96f673rbpmc1-gse1

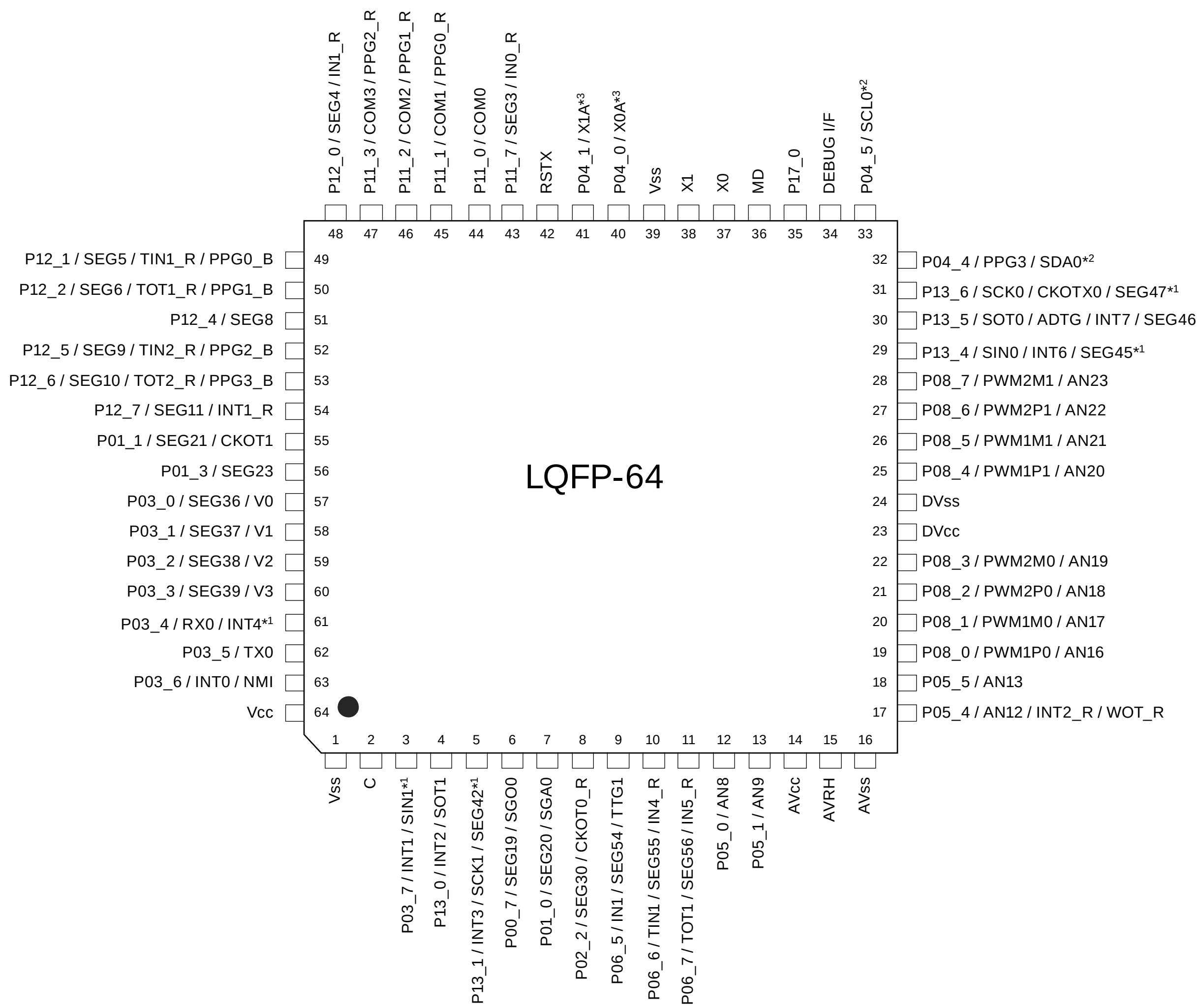
Contents

2. Block Diagram



3. Pin Assignment

(Top view)



(FPT-64P-M23/M24)

*1: CMOS input level only

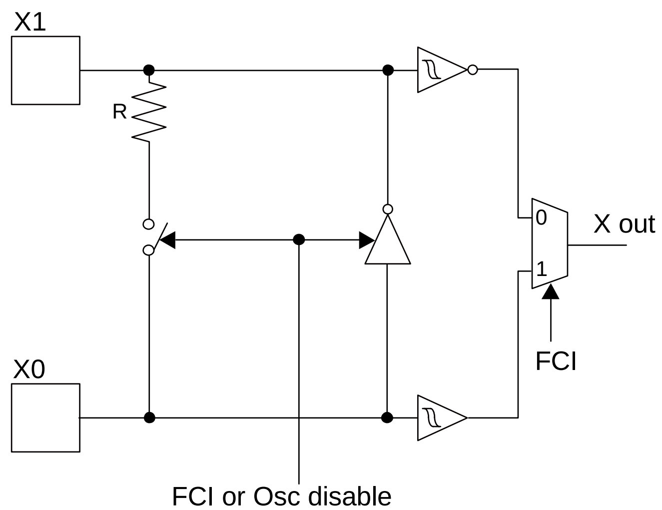
*2: CMOS input level only for I^2C

*3: Please set ROM Configuration Block (RCB) to use the subclock.

Other than those above, general-purpose pins have only Automotive input level.

Pin name	Feature	Description
Vn	LCD	LCD voltage reference pin
Vcc	Supply	Power supply pin
Vss	Supply	Power supply pin
WOT_R	RTC	Relocated Real Time clock output pin
X0	Clock	Oscillator input pin
X0A	Clock	Subclock Oscillator input pin
X1	Clock	Oscillator output pin
X1A	Clock	Subclock Oscillator output pin

6. I/O Circuit Type

Type	Circuit	Remarks
A		High-speed oscillation circuit: • Programmable between oscillation mode (external crystal or resonator connected to X0/X1 pins) and Fast external Clock Input (FCI) mode (external clock connected to X0 pin) • Feedback resistor = approx. 1.0MΩ • The amplitude: 1.8V±0.15V to operate by the internal supply voltage

8. RAMSTART Addresses

Devices	Bank 0 RAM size	RAMSTART0
MB96F673 MB96F675	4KB	$00{:}7200_H$

11. Interrupt Vector Table

Vector number	Offset in vector table	Vector name	Cleared by DMA	Index in ICR to program	Description
0	$3FC_H$	CALLV0	No	-	CALLV instruction
1	$3F8_H$	CALLV1	No	-	CALLV instruction
2	$3F4_H$	CALLV2	No	-	CALLV instruction
3	$3F0_H$	CALLV3	No	-	CALLV instruction
4	$3EC_H$	CALLV4	No	-	CALLV instruction
5	$3E8_H$	CALLV5	No	-	CALLV instruction
6	$3E4_H$	CALLV6	No	-	CALLV instruction
7	$3E0_H$	CALLV7	No	-	CALLV instruction
8	$3DC_H$	RESET	No	-	Reset vector
9	$3D8_H$	INT9	No	-	INT9 instruction
10	$3D4_H$	EXCEPTION	No	-	Undefined instruction execution
11	$3D0_H$	NMI	No	-	Non-Maskable Interrupt
12	$3CC_H$	DLY	No	12	Delayed Interrupt
13	$3C8_H$	RC_TIMER	No	13	RC Clock Timer
14	$3C4_H$	MC_TIMER	No	14	Main Clock Timer
15	$3C0_H$	SC_TIMER	No	15	Sub Clock Timer
16	$3BC_H$	LVDI	No	16	Low Voltage Detector
17	$3B8_H$	EXTINT0	Yes	17	External Interrupt 0
18	$3B4_H$	EXTINT1	Yes	18	External Interrupt 1
19	$3B0_H$	EXTINT2	Yes	19	External Interrupt 2
20	$3AC_H$	EXTINT3	Yes	20	External Interrupt 3
21	$3A8_H$	EXTINT4	Yes	21	External Interrupt 4
22	$3A4_H$	-	-	22	Reserved
23	$3A0_H$	EXTINT6	Yes	23	External Interrupt 6
24	$39C_H$	EXTINT7	Yes	24	External Interrupt 7
25	398_H	-	-	25	Reserved
26	394_H	-	-	26	Reserved
27	390_H	-	-	27	Reserved
28	$38C_H$	-	-	28	Reserved
29	388_H	-	-	29	Reserved
30	384_H	-	-	30	Reserved
31	380_H	-	-	31	Reserved
32	$37C_H$	-	-	32	Reserved
33	378_H	CAN0	No	33	CAN Controller 0
34	374_H	-	-	34	Reserved
35	370_H	-	-	35	Reserved
36	$36C_H$	-	-	36	Reserved
37	368_H	-	-	37	Reserved
38	364_H	PPG0	Yes	38	Programmable Pulse Generator 0
39	360_H	PPG1	Yes	39	Programmable Pulse Generator 1

Vector number	Offset in vector table	Vector name	Cleared by DMA	Index in ICR to program	Description
81	$2B8_H$	-	-	81	Reserved
82	$2B4_H$	-	-	82	Reserved
83	$2B0_H$	-	-	83	Reserved
84	$2AC_H$	-	-	84	Reserved
85	$2A8_H$	-	-	85	Reserved
86	$2A4_H$	-	-	86	Reserved
87	$2A0_H$	-	-	87	Reserved
88	$29C_H$	-	-	88	Reserved
89	298_H	FRT0	Yes	89	Free-Running Timer 0
90	294_H	FRT1	Yes	90	Free-Running Timer 1
91	290_H	-	-	91	Reserved
92	$28C_H$	-	-	92	Reserved
93	288_H	RTC0	No	93	Real Time Clock
94	284_H	CAL0	No	94	Clock Calibration Unit
95	280_H	SG0	No	95	Sound Generator 0
96	$27C_H$	IIC0	Yes	96	I^2C interface 0
97	278_H	-	-	97	Reserved
98	274_H	ADC0	Yes	98	A/D Converter 0
99	270_H	-	-	99	Reserved
100	$26C_H$	-	-	100	Reserved
101	268_H	LINR0	Yes	101	LIN USART 0 RX
102	264_H	LINT0	Yes	102	LIN USART 0 TX
103	260_H	LINR1	Yes	103	LIN USART 1 RX
104	$25C_H$	LINT1	Yes	104	LIN USART 1 TX
105	258_H	-	-	105	Reserved
106	254_H	-	-	106	Reserved
107	250_H	-	-	107	Reserved
108	$24C_H$	-	-	108	Reserved
109	248_H	-	-	109	Reserved
110	244_H	-	-	110	Reserved
111	240_H	-	-	111	Reserved
112	$23C_H$	-	-	112	Reserved
113	238_H	-	-	113	Reserved
114	234_H	-	-	114	Reserved
115	230_H	-	-	115	Reserved
116	$22C_H$	-	-	116	Reserved
117	228_H	-	-	117	Reserved
118	224_H	-	-	118	Reserved
119	220_H	-	-	119	Reserved
120	$21C_H$	-	-	120	Reserved

12. Handling Precautions

Any semiconductor devices have inherently a certain rate of failure. The possibility of failure is greatly affected by the conditions in which they are used (circuit conditions, environmental conditions, etc.). This page describes precautions that must be observed to minimize the chance of failure and to obtain higher reliability from your Cypress semiconductor devices.

12.1 Precautions for Product Design

This section describes precautions when designing electronic equipment using semiconductor devices.

■Absolute Maximum Ratings

Semiconductor devices can be permanently damaged by application of stress (voltage, current, temperature, etc.) in excess of certain established limits, called absolute maximum ratings. Do not exceed these ratings.

■Recommended Operating Conditions

Recommended operating conditions are normal operating ranges for the semiconductor device. All the device's electrical characteristics are warranted when operated within these ranges.

Always use semiconductor devices within the recommended operating conditions. Operation outside these ranges may adversely affect reliability and could result in device failure.

No warranty is made with respect to uses, operating conditions, or combinations not represented on the data sheet. Users considering application outside the listed conditions are advised to contact their sales representative beforehand.

■Processing and Protection of Pins

These precautions must be followed when handling the pins which connect semiconductor devices to power supply and input/output functions.

1. Preventing Over-Voltage and Over-Current Conditions

   Exposure to voltage or current levels in excess of maximum ratings at any pin is likely to cause deterioration within the device, and in extreme cases leads to permanent damage of the device. Try to prevent such overvoltage or over-current conditions at the design stage.

2. Protection of Output Pins

   Shorting of output pins to supply pins or other output pins, or connection to large capacitance can cause large current flows. Such conditions if present for extended periods of time can damage the device.
   Therefore, avoid this type of connection.

3. Handling of Unused Input Pins

   Unconnected input pins with very high impedance levels can adversely affect stability of operation. Such pins should be connected through an appropriate resistance to a power supply pin or ground pin.

■Latch-up

Semiconductor devices are constructed by the formation of P-type and N-type areas on a substrate. When subjected to abnormally high voltages, internal parasitic PNPN junctions (called thyristor structures) may be formed, causing large current levels in excess of several hundred mA to flow continuously at the power supply pin. This condition is called latch-up.

CAUTION: The occurrence of latch-up not only causes loss of reliability in the semiconductor device, but can cause injury or damage from high heat, smoke or flame. To prevent this from happening, do the following:

1. Be sure that voltages applied to pins do not exceed the absolute maximum ratings. This should include attention to abnormal noise, surge levels, etc.
2. Be sure that abnormal current flows do not occur during the power-on sequence.

■Observance of Safety Regulations and Standards

Most countries in the world have established standards and regulations regarding safety, protection from electromagnetic interference, etc. Customers are requested to observe applicable regulations and standards in the design of products.

■Fail-Safe Design

Any semiconductor devices have inherently a certain rate of failure. You must protect against injury, damage or loss from such failures by incorporating safety design measures into your facility and equipment such as redundancy, fire protection, and prevention of over-current levels and other abnormal operating conditions.

■Static Electricity

Because semiconductor devices are particularly susceptible to damage by static electricity, you must take the following precautions:

1. Maintain relative humidity in the working environment between 40% and 70%. Use of an apparatus for ion generation may be needed to remove electricity.
2. Electrically ground all conveyors, solder vessels, soldering irons and peripheral equipment.
3. Eliminate static body electricity by the use of rings or bracelets connected to ground through high resistance (on the level of 1 MΩ).
   Wearing of conductive clothing and shoes, use of conductive floor mats and other measures to minimize shock loads is recommended.
4. Ground all fixtures and instruments, or protect with anti-static measures.
5. Avoid the use of styrofoam or other highly static-prone materials for storage of completed board assemblies.

12.3 Precautions for Use Environment

Reliability of semiconductor devices depends on ambient temperature and other conditions as described above.

For reliable performance, do the following:

1. Humidity

   Prolonged use in high humidity can lead to leakage in devices as well as printed circuit boards. If high humidity levels are anticipated, consider anti-humidity processing.
2. Discharge of Static Electricity

   When high-voltage charges exist close to semiconductor devices, discharges can cause abnormal operation. In such cases, use anti-static measures or processing to prevent discharges.
3. Corrosive Gases, Dust, or Oil

   Exposure to corrosive gases or contact with dust or oil may lead to chemical reactions that will adversely affect the device. If you use devices in such conditions, consider ways to prevent such exposure or to protect the devices.
4. Radiation, Including Cosmic Radiation

   Most devices are not designed for environments involving exposure to radiation or cosmic radiation. Users should provide shielding as appropriate.
5. Smoke, Flame

CAUTION: Plastic molded devices are flammable, and therefore should not be used near combustible substances. If devices begin to smoke or burn, there is danger of the release of toxic gases.

Customers considering the use of Cypress products in other special environmental conditions should consult with sales representatives.

13. Handling Devices

Special care is required for the following when handling the device:

- Latch-up prevention
- Unused pins handling
- External clock usage
- Notes on PLL clock mode operation
- Power supply pins (Vcc/Vss)
- Crystal oscillator and ceramic resonator circuit
- Turn on sequence of power supply to A/D converter and analog inputs
- Pin handling when not using the A/D converter
- Notes on Power-on
- Stabilization of power supply voltage
- SMC power supply pins
- Serial communication
- Mode Pin (MD)

13.1 Latch-up prevention

CMOS IC chips may suffer latch-up under the following conditions:

- A voltage higher than V_{CC} or lower than V_{SS} is applied to an input or output pin.
- A voltage higher than the rated voltage is applied between Vcc pins and Vss pins.
- The AV_{CC} power supply is applied before the V_{CC} voltage.

Latch-up may increase the power supply current dramatically, causing thermal damages to the device.

For the same reason, extra care is required to not let the analog power-supply voltage (AV_{CC}, AVRH) exceed the digital power-supply voltage.

13.2 Unused pins handling

Unused input pins can be left open when the input is disabled (corresponding bit of Port Input Enable register

PIER = 0).

Leaving unused input pins open when the input is enabled may result in misbehavior and possible permanent

damage of the device. To prevent latch-up, they must therefore be pulled up or pulled down through resistors which should be more than 2kΩ.

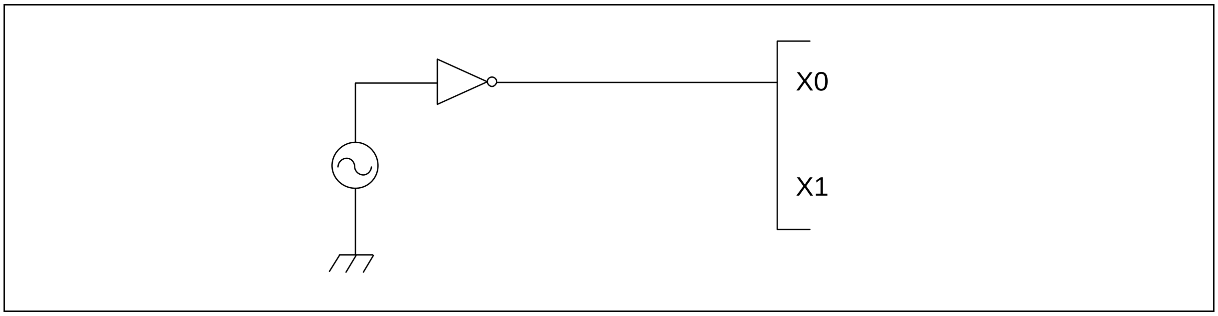
Unused bidirectional pins can be set either to the output state and be then left open, or to the input state with

either input disabled or external pull-up/pull-down resistor as described above.

13.3 External clock usage
The permitted frequency range of an external clock depends on the oscillator type and configuration.

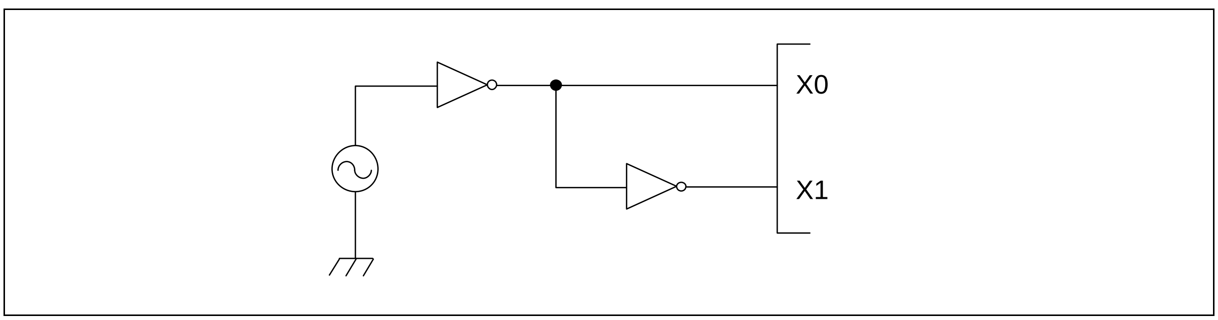
See AC Characteristics for detailed modes and frequency limits. Single and opposite phase external clocks must be connected as follows:

13.3.1 Single phase external clock for Main oscillator
When using a single phase external clock for the Main oscillator, X0 pin must be driven and X1 pin left open.
And supply 1.8V power to the external clock.



13.3.2 Single phase external clock for Sub oscillator
When using a single phase external clock for the Sub oscillator, “External clock mode” must be selected and X0A/P04_0 pin must be driven. X1A/P04_1 pin can be configured as GPIO.

13.3.3 Opposite phase external clock
When using an opposite phase external clock, X1 (X1A) pins must be supplied with a clock signal which has the opposite phase to the X0 (X0A) pins. Supply level on X0 and X1 pins must be 1.8V.



13.4 Notes on PLL clock mode operation
If the microcontroller is operated with PLL clock mode and no external oscillator is operating or no external clock is supplied, the microcontroller attempts to work with the free oscillating PLL. Performance of this operation, however, cannot be guaranteed.

13.5 Power supply pins (Vcc/Vss)
It is required that all V_{CC}-level as well as all V_{SS}-level power supply pins are at the same potential. If there is more than one V_{CC} or V_{SS} level, the device may operate incorrectly or be damaged even within the guaranteed operating range.

Vcc and Vss pins must be connected to the device from the power supply with lowest possible impedance.

The smoothing capacitor at Vcc pin must use the one of a capacity value that is larger than Cs.

Besides this, as a measure against power supply noise, it is required to connect a bypass capacitor of about 0.1μF between Vcc and Vss pins as close as possible to Vcc and Vss pins.

14. Electrical Characteristics

14.1 Absolute Maximum Ratings

Parameter	Symbol	Condition	Rating Min	Rating Max	Unit	Remarks
Power supply voltage*[1]	V_{CC}	-	V_{SS} - 0.3	V_{SS} + 6.0	V	
Analog power supply voltage*[1]	AV_{CC}	-	V_{SS} - 0.3	V_{SS} + 6.0	V	$V_{CC} = AV_{CC}$*[2]
Analog reference voltage*[1]	AVRH	-	V_{SS} - 0.3	V_{SS} + 6.0	V	$AV_{CC} \geq AVRH$, $AVRH \geq AV_{SS}$
SMC Power supply*[1]	DV_{CC}	-	V_{SS} - 0.3	V_{SS} + 6.0	V	$V_{CC} = AV_{CC} = DV_{CC}$*[2]
LCD power supply voltage*[1]	V0 to V3	-	V_{SS} - 0.3	V_{SS} + 6.0	V	V0 to V3 must not exceed V_{CC}
Input voltage*[1]	V_I	-	V_{SS} - 0.3	V_{SS} + 6.0	V	$V_I \leq (D)V_{CC} + 0.3V$*[3]
Output voltage*[1]	V_O	-	V_{SS} - 0.3	V_{SS} + 6.0	V	$V_O \leq (D)V_{CC} + 0.3V$*[3]
Maximum Clamp Current	I_{CLAMP}	-	-4.0	+4.0	mA	Applicable to general purpose I/O pins *[4]
Total Maximum Clamp Current	$\Sigma\lvert I_{CLAMP}\rvert$	-	-	16	mA	Applicable to general purpose I/O pins *[4]
"L" level maximum output current	I_{OL}	-	-	15	mA	Normal port
	I_{OLSMC}	T_A= -40°C	-	52	mA	High current port
		T_A= +25°C	-	39	mA	
		T_A= +85°C	-	32	mA	
		T_A= +105°C	-	30	mA	
"L" level average output current	I_{OLAV}	-	-	4	mA	Normal port
	$I_{OLAVSMC}$	T_A= -40°C	-	40	mA	High current port
		T_A= +25°C	-	30	mA	
		T_A= +85°C	-	25	mA	
		T_A= +105°C	-	23	mA	
"L" level maximum overall output current	ΣI_{OL}	-	-	34	mA	Normal port
	ΣI_{OLSMC}	-	-	180	mA	High current port
"L" level average overall output current	ΣI_{OLAV}	-	-	17	mA	Normal port
	$\Sigma I_{OLAVSMC}$	-	-	90	mA	High current port
"H" level maximum output current	I_{OH}	-	-	-15	mA	Normal port
	I_{OHSMC}	T_A= -40°C	-	-52	mA	High current port
		T_A= +25°C	-	-39	mA	
		T_A= +85°C	-	-32	mA	
		T_A= +105°C	-	-30	mA	
"H" level average output current	I_{OHAV}	-	-	-4	mA	Normal port
	$I_{OHAVSMC}$	T_A= -40°C	-	-40	mA	High current port
		T_A= +25°C	-	-30	mA	
		T_A= +85°C	-	-25	mA	
		T_A= +105°C	-	-23	mA	
"H" level maximum overall output current	ΣI_{OH}	-	-	-34	mA	Normal port
	ΣI_{OHSMC}	-	-	-180	mA	High current port
"H" level average overall output current	ΣI_{OHAV}	-	-	-17	mA	Normal port
	$\Sigma I_{OHAVSMC}$	-	-	-90	mA	High current port
Power consumption*[5]	P_D	T_A= +105°C	-	281*[6]	mW	
Operating ambient temperature	T_A	-	-40	+105	°C	
Storage temperature	T_{STG}	-	-55	+150	°C	

14.3 DC Characteristics

14.3.1 Current Rating

($V_{CC} = AV_{CC} = DV_{CC}$ = 2.7V to 5.5V, $V_{SS} = AV_{SS} = DV_{SS}$ = 0V, T_A = - 40°C to + 105°C)

Parameter	Symbol	Pin name	Conditions	Value Min	Value Typ	Value Max	Unit	Remarks
Power supply current in Run modes[*1]	I_{CCPLL}	Vcc	PLL Run mode with CLKS1/2 = CLKB = CLKP1/2 = 32MHz Flash 0 wait (CLKRC and CLKSC stopped)	-	25	-	mA	T_A = +25°C
				-	-	34	mA	T_A = +105°C
	I_{CCMAIN}		Main Run mode with CLKS1/2 = CLKB = CLKP1/2 = 4MHz Flash 0 wait (CLKPLL, CLKSC and CLKRC stopped)	-	3.5	-	mA	T_A = +25°C
				-	-	7.5	mA	T_A = +105°C
	I_{CCRCH}		RC Run mode with CLKS1/2 = CLKB = CLKP1/2 = CLKRC = 2MHz Flash 0 wait (CLKMC, CLKPLL and CLKSC stopped)	-	1.7	-	mA	T_A = +25°C
				-	-	5.5	mA	T_A = +105°C
	I_{CCRCL}		RC Run mode with CLKS1/2 = CLKB = CLKP1/2 = CLKRC = 100kHz Flash 0 wait (CLKMC, CLKPLL and CLKSC stopped)	-	0.15	-	mA	T_A = +25°C
				-	-	3.2	mA	T_A = +105°C
	I_{CCSUB}		Sub Run mode with CLKS1/2 = CLKB = CLKP1/2 = 32kHz Flash 0 wait (CLKMC, CLKPLL and CLKRC stopped)	-	0.1	-	mA	T_A = +25°C
				-	-	3	mA	T_A = +105°C

Parameter	Symbol	Pin name	Conditions	Value			Unit	Remarks
				Min	Typ	Max		
Power supply current in Sleep modes[*1]	I_{CCSPLL}	Vcc	PLL Sleep mode with CLKS1/2 = CLKP1/2 = 32MHz (CLKRC and CLKSC stopped)	-	6.5	-	mA	T_A = +25°C
				-	-	13	mA	T_A = +105°C
	$I_{CCSMAIN}$		Main Sleep mode with CLKS1/2 = CLKP1/2 = 4MHz, SMCR:LPMSS = 0 (CLKPLL, CLKRC and CLKSC stopped)	-	0.9	-	mA	T_A = +25°C
				-	-	4	mA	T_A = +105°C
	I_{CCSRCH}		RC Sleep mode with CLKS1/2 = CLKP1/2 = CLKRC = 2MHz, SMCR:LPMSS = 0 (CLKMC, CLKPLL and CLKSC stopped)	-	0.5	-	mA	T_A = +25°C
				-	-	3.5	mA	T_A = +105°C
	I_{CCSRCL}		RC Sleep mode with CLKS1/2 = CLKP1/2 = CLKRC = 100kHz (CLKMC, CLKPLL and CLKSC stopped)	-	0.06	-	mA	T_A = +25°C
				-	-	2.7	mA	T_A = +105°C
	I_{CCSSUB}		Sub Sleep mode with CLKS1/2 = CLKP1/2 = 32kHz, (CLKMC, CLKPLL and CLKRC stopped)	-	0.04	-	mA	T_A = +25°C
				-	-	2.5	mA	T_A = +105°C
Power supply current in Timer modes[*2]	I_{CCTPLL}		PLL Timer mode with CLKPLL = 32MHz (CLKRC and CLKSC stopped)	-	1800	2245	μA	T_A = +25°C
				-	-	3140	μA	T_A = +105°C
	$I_{CCTMAIN}$		Main Timer mode with CLKMC = 4MHz, SMCR:LPMSS = 0 (CLKPLL, CLKRC and CLKSC stopped)	-	285	325	μA	T_A = +25°C
				-	-	1055	μA	T_A = +105°C
	I_{CCTRCH}		RC Timer mode with CLKRC = 2MHz, SMCR:LPMSS = 0 (CLKPLL, CLKMC and CLKSC stopped)	-	160	210	μA	T_A = +25°C
				-	-	970	μA	T_A = +105°C
	I_{CCTRCL}		RC Timer mode with CLKRC = 100kHz (CLKPLL, CLKMC and CLKSC stopped)	-	30	70	μA	T_A = +25°C
				-	-	820	μA	T_A = +105°C
	I_{CCTSUB}		Sub Timer mode with CLKSC = 32kHz (CLKMC, CLKPLL and CLKRC stopped)	-	25	55	μA	T_A = +25°C
				-	-	800	μA	T_A = +105°C

Parameter	Symbol	Pin name	Conditions	Value			Unit	Remarks
				Min	Typ	Max		
Input leak current	I_{IL}	Pnn_m	$V_{SS} < V_I < V_{CC}$ $AV_{SS} < V_I <$ AV_{CC}, AVRH	- 1	-	+ 1	μA	Single port pin except high current output I/O for SMC
		P08_m	$DV_{SS} < V_I < DV_{CC}$ $AV_{SS} < V_I <$ AV_{CC}, AVRH	- 3	-	+ 3	μA	
Total LCD leak current	$\Sigma\|I_{ILCD}\|$	All SEG/ COM pin	V_{CC} = 5.0V	-	0.5	10	μA	Maximum leakage current of all LCD pins
Internal LCD divide resistance	R_{LCD}	Between V3 and V2, V2 and V1, V1 and V0	V_{CC} = 5.0V	6.25	12.5	25	kΩ	
Pull-up resistance value	R_{PU}	Pnn_m	V_{CC} = 5.0V ±10%	25	50	100	kΩ	
Pull-down resistance value	R_{DOWN}	P08_m	V_{CC} = 5.0V ±10%	25	50	100	kΩ	
Input capacitance	C_{IN}	Other than C, Vcc, Vss, DVcc DVss, AVcc, AVss, AVRH, P08_m	-	-	5	15	pF	
		P08_m	-	-	15	30	pF	

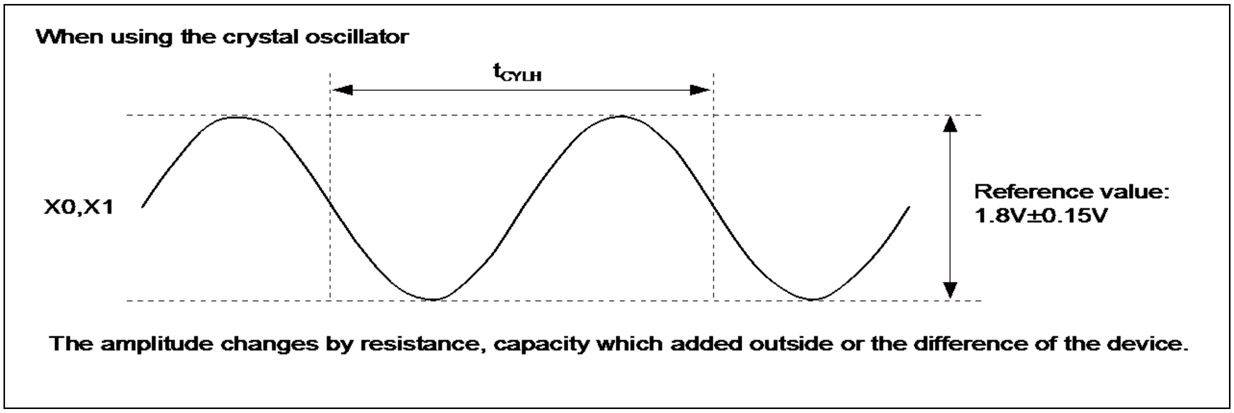
*: In the case of driving stepping motor directly or high current outputs, set "1" to the bit in the Port High Drive Register (PHDRnn:HDx="1").

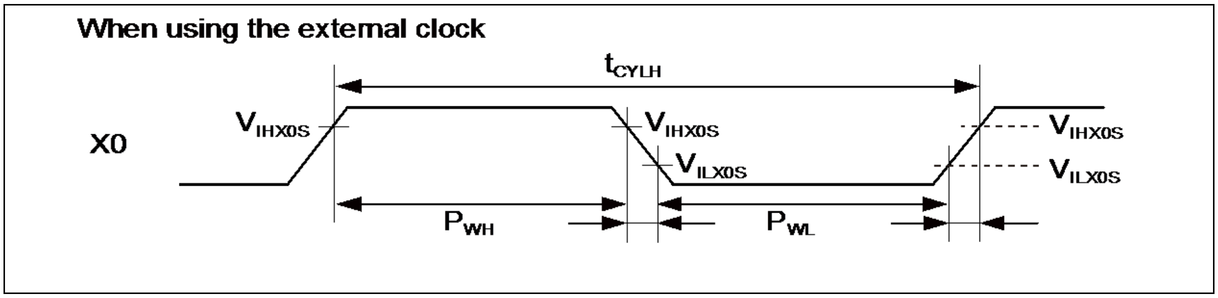
14.4 AC Characteristics

14.4.1 Main Clock Input Characteristics

(V_{CC} = AV_{CC} = DV_{CC} = 2.7V to 5.5V, VD=1.8V±0.15V, V_{SS} = AV_{SS} = DV_{SS} = 0V, T_A = - 40°C to + 105°C)

Parameter	Symbol	Pin name	Value			Unit	Remarks
			Min	Typ	Max		
Input frequency	f_C	X0, X1	4	-	8	MHz	When using a crystal oscillator, PLL off
			-	-	8	MHz	When using an opposite phase external clock, PLL off
			4	-	8	MHz	When using a crystal oscillator or opposite phase external clock, PLL on
Input frequency	f_{FCI}	X0	-	-	8	MHz	When using a single phase external clock in “Fast Clock Input mode”, PLL off
			4	-	8	MHz	When using a single phase external clock in “Fast Clock Input mode”, PLL on
Input clock cycle	t_{CYLH}	-	125	-	-	ns	
Input clock pulse width	P_{WH}, P_{WL}	-	55	-	-	ns	





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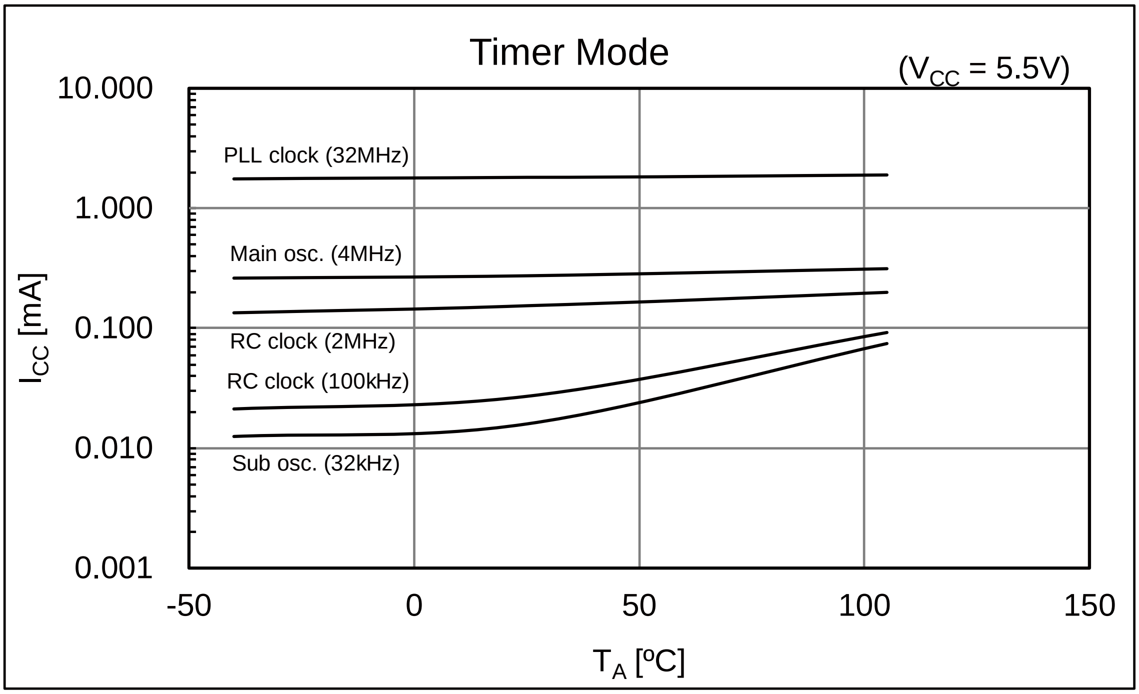
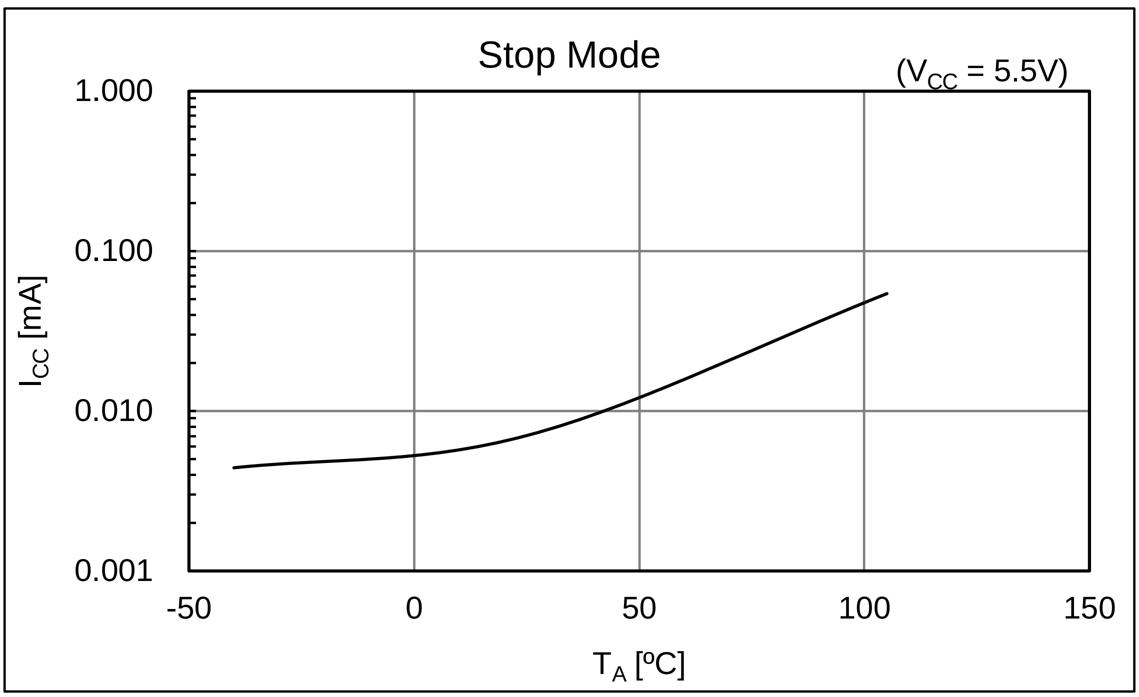
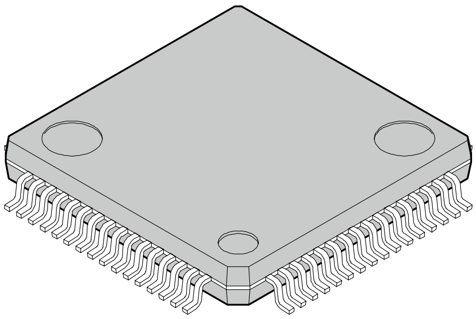

Timer Mode
(VCC = 5.5V)
10.000
1.000
0.100
0.010
0.001
ICC [mA]
PLL clock (32MHz)
Main osc. (4MHz)
RC clock (2MHz)
RC clock (100kHz)
Sub osc. (32kHz)
-50
0
50
100
150
TA [ºC]


Stop Mode
(VCC = 5.5V)
1.000
0.100
0.010
0.001
ICC [mA]
-50
0
50
100
150
TA [ºC]

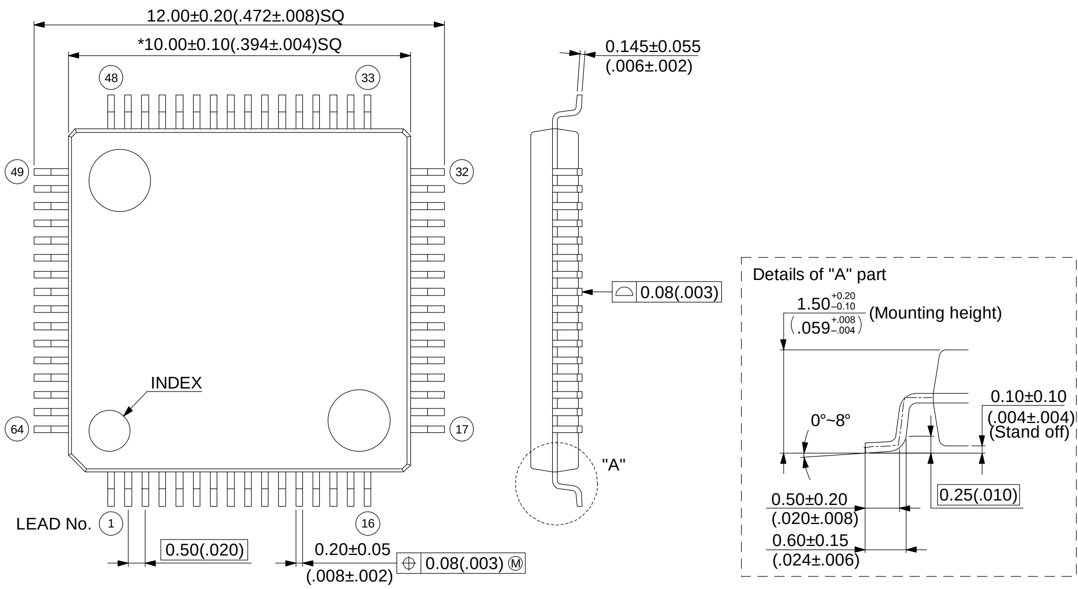
■Used setting

Mode	Selected Source Clock	Clock/Regulator and FLASH Settings
Run mode	PLL	CLKS1 = CLKS2 = CLKB = CLKP1 = CLKP2 = 32MHz
	Main osc.	CLKS1 = CLKS2 = CLKB = CLKP1 = CLKP2 = 4MHz
	RC clock fast	CLKS1 = CLKS2 = CLKB = CLKP1 = CLKP2 = 2MHz
	RC clock slow	CLKS1 = CLKS2 = CLKB = CLKP1 = CLKP2 = 100kHz
	Sub osc.	CLKS1 = CLKS2 = CLKB = CLKP1 = CLKP2 = 32kHz
Sleep mode	PLL	CLKS1 = CLKS2 = CLKP1 = CLKP2 = 32MHz Regulator in High Power Mode, (CLKB is stopped in this mode)
	Main osc.	CLKS1 = CLKS2 = CLKP1 = CLKP2 = 4MHz Regulator in High Power Mode, (CLKB is stopped in this mode)
	RC clock fast	CLKS1 = CLKS2 = CLKP1 = CLKP2 = 2MHz Regulator in High Power Mode, (CLKB is stopped in this mode)
	RC clock slow	CLKS1 = CLKS2 = CLKP1 = CLKP2 = 100kHz Regulator in Low Power Mode, (CLKB is stopped in this mode)
	Sub osc.	CLKS1 = CLKS2 = CLKP1 = CLKP2 = 32kHz Regulator in Low Power Mode, (CLKB is stopped in this mode)
Timer mode	PLL	CLKMC = 4MHz, CLKPLL = 32MHz (System clocks are stopped in this mode) Regulator in High Power Mode, FLASH in Power-down / reset mode
	Main osc.	CLKMC = 4MHz (System clocks are stopped in this mode) Regulator in High Power Mode, FLASH in Power-down / reset mode
	RC clock fast	CLKMC = 2MHz (System clocks are stopped in this mode) Regulator in High Power Mode, FLASH in Power-down / reset mode
	RC clock slow	CLKMC = 100kHz (System clocks are stopped in this mode) Regulator in Low Power Mode, FLASH in Power-down / reset mode
	Sub osc.	CLKMC = 32 kHz (System clocks are stopped in this mode) Regulator in Low Power Mode, FLASH in Power-down / reset mode
Stop mode	stopped	(All clocks are stopped in this mode) Regulator in Low Power Mode, FLASH in Power-down / reset mode

64-pin plastic LQFP	Lead pitch	0.50 mm
	Package width × package length	10.0 × 10.0 mm
	Lead shape	Gullwing
	Sealing method	Plastic mold
	Mounting height	1.70 mm MAX
	Weight	0.32 g
(FPT-64P-M24)	Code (Reference)	P-LFQFP64-10×10-0.50

64-pin plastic LQFP
(FPT-64P-M24)

Note 1) * : These dimensions do not include resin protrusion.
Note 2) Pins width and pins thickness include plating thickness.
Note 3) Pins width do not include tie bar cutting remainder.



Dimensions in mm (inches).
Note: The values in parentheses are reference values